

SOD-123S (MINI SMA)

# 2.0 LOW VF SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER 40V-100V

#### **DESCRIPTION:**



The ALP2L40-MS thru ALP2L100-MS is 2.0A Low VF Surface Mount Schottky Barrier Rectifier – 40V - 100V are low profile package, Ideal for automated placement and guarding for overvoltage protection. Use in low voltage high frequency inverters, freewheeling, converters, and Telecomunication applications.

#### **FEATURES:**

- High current density Schottky
- Low profile surface mounted application in order to optimize board space
- Tiny plastic SMD package
- Low power loss, high efficiency
- High current capability, low forward voltage drops
- High surge capability
- Lead-free parts meet RoHS requirements
- Suffix "-H" indicates Halogen free parts, ex. ALP2L40-MS-H

#### **APPLICATIONS:**

- General purpose rectification of lighting
- Power supplies
- Inverters & Converters
- Freewheeling diodes for consumer
- Automotive
- Telecommunication

#### **MECHANICAL CHARACTERISTICS**

- Epoxy: UL94-V0 rated flame retardant.
- Case: Molded plastic, SOD-123S/MINI SMA.
- Terminals: Plated terminals, Solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode except bi-directional models
- Mounting Position: Any.
- Approximate Weight: 0.0155 grams.



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### **TYPICAL DEVICE CHARACTERISTICS**

<b>MAXIMUM RATINGS</b> ( $T_A = 25$ °C unless otherwise noted)						
PARAMETER	SYMBOL	ALP2L40-MS	ALP2L45-MS	ALP2L60-MS	ALP2L100-MS	UNITS
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	40	45	60	100	Volts
Maximum RMS voltage	$V_{RMS}$	28	31.5	42	70	Volts
Maximum continuous reverse voltage	V <sub>R</sub>	40	45	60	100	Volts
Maximum average forward rectified current	lo	2.0			Amps	
Non-repetitive Peak forward surge current 8.3 ms single half sine-wave (JEDEC Method)	I <sub>FSM</sub>	ъм 50			Amps	
Operating junction temperature range	Τı	-55 to +125 -55 to +150			°C	
Storage temperature range	Т <sub>STG</sub>	-65 to +175			°C	

ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)							
PARAMETER	TEST CONDITIONS	SYMBOL	ALP2L40-MS	ALP2L45-MS	ALP2L60-MS	ALP2L100-MS	UNIT
Maximum instantaneous forward voltage	I <sub>F</sub> = 2.0A	VF	0.45	0.45	0.55	0.75	Volts
Maximum reverse		0.5				mA	
leakage current at rated V <sub>R</sub>	T <sub>J</sub> = 100 °C	I <sub>R</sub>	10				mA

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	ALP2L40-MS	ALP2L45-MS	ALP2L60-MS	ALP2L100-MS	UNIT
Typical thermal resistance (1) junction to ambient	$R_{\theta JA}$	^ 75 °C/W				
Typical thermal resistance (1) junction to case	R <sub>θJc</sub> 35 °C/W					
Note:  (1) Mounted on FR-4 PCB Copper, minimum recommended pad layout.						

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#### **TYPICAL DEVICE CHARACTERISTICS CURVES**

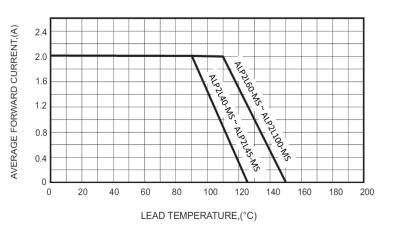


Fig1. TYPICAL FORWARD CURRENT DERATING CURVE

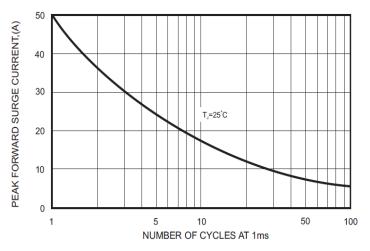


Fig3. MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

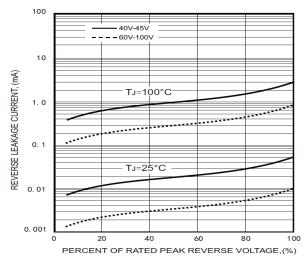


Fig.5 TYPICAL REVERSE CHARACTERISTICS

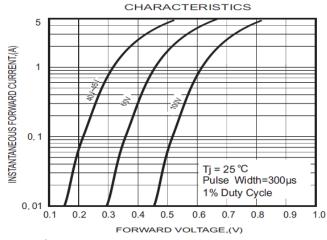


Fig2. TYPICAL FORWARD CHARACTERISTICS

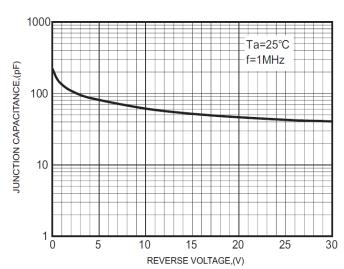


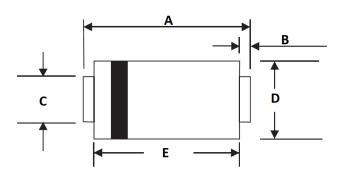
Fig4. TYPICAL JUNCTION CAPACITANCE

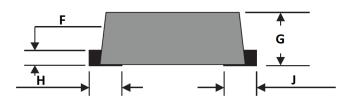
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#### **PACKAGE INFORMATION**

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beyond boundaries...

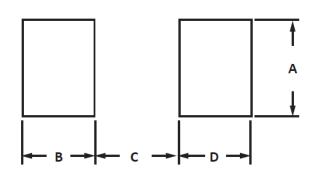




OUTLINE DIMENSIONS					
DIM	MILLIMET	TERS	INCHES		
	MIN	MAX	MIN	MAX	
А	3.50	3.90	0.138	0.154	
В	0.4	45	0.0	)18	
С	0.70	1.10	0.028	0.044	
D	1.60	2.00	0.063	0.079	
Е	2.60	3.00	0.103	0.119	
F	0.18	0.22	0.007	0.009	
G	0.90	1.00	0.036	0.040	
Н	0.80		0.032		
J	0.80		0.032		
·					

#### **NOTES**

<sup>1.</sup> Dimensions are exclusive of mold flash and metal burrs.



PAD LAYOUT DIMENSIONS				
DIM	MILLIMETERS	INCHES		
	Тур.	Тур.		
А	1.10	0.044		
В	1.00	0.040		
С	2.00	0.079		
D	1.00	0.040		

#### PINNING INFORMATION

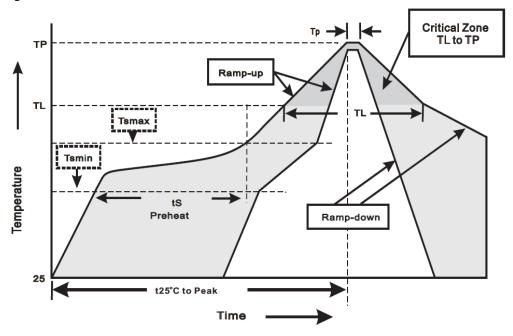
PIN	SIMPLIFIED OUTLINE	SYMBOL	
Pin1 Cathode Pin2 Anode	1 [ 2	12	

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### **SOLDERING PARAMETERS**

### SUGGESTED THERMAL PROFILES FOR SOLDERING PROCESSES

- 1. Storage environment: Temperature=5 °C~40 °C Humidity=55% ±25%
- 2. Reflow soldering of surface-mount devices



#### 3. Reflow soldering

PROFILE FEATURE	SOLDERING CONDITION
Average ramp-up rate (T <sub>L</sub> to T <sub>P</sub> )	<3 °C/sec
Preheat	
- Temperature Min (T <sub>smin</sub> )	150 °C
- Temperature Max (T <sub>smax</sub> )	200 °C
- Time (min to max) (t₅)	60 ~ 120 sec
T <sub>smax</sub> to T <sub>L</sub>	
- Ramp-upRate	<3 °C/sec
Time maintained above:	
- Temperature (T∟)	217 °C
- Time(tL)	60 ~ 260 sec
Peak Temperature (T <sub>P</sub> )	255 °C-0/+5 °C
Time within 5 °C of actual Peak Temperature(tP)	10 ~ 30 sec
Ramp-down Rate	<6 °C/sec
Time 25 °C to Peak Temperature	<6 minutes



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### PRODUCT HIGH RELIABLITY TEST CAPABILITIES

ITEM	TEST CONDITIONS	STANDARD
Solder Resistance	At 260±5°C for 10±2Sec.	MIL-STD-750D METHOD-2031
Solderability	At 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
High Temperature Reverse Bias	$V_R$ = 80% rate at $T_J$ =150° for 168 hrs.	MIL-STD-750D METHOD-1038
Forward Operation Life	Rated average rectifier current at T <sub>A</sub> =25 C for 500hrs	MIL-STD-750D METHOD-1027
Intermittent Operation Life	T <sub>A</sub> = 25 °C, I <sub>F</sub> = I <sub>O</sub> On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
Pressure Cooker	15P <sub>SIG</sub> at T <sub>A</sub> =121°C for 4Hrs	JESD22-A102
Temperature Cycling	-55°C to +125°C dwelled for 30min and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
Forward Surge	1.0ms square-wave, one surge.	MIL-STD-750D METHOD-4066-2
Humidity	At T <sub>A</sub> =85°C, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
High Temperature Storage Life	At 175°C for 1000hrs.	MIL-STD-750D METHOD-1031



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#### **CUSTOMER NOTE:**

#### **DISCLAIMER**

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- 1. ALPINESEMI™ Semiconductor Devices are RoHS compliant and hence customers are requested to dispose as per the prevailing Environmental Legislation put forth in their specific country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).



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